## IN THE CLAIMS

Please cancel Claim 9.

## 1-9. (Cancelled)

- (Currently Amended) A method comprising polishing a composite material containing silica and silicon nitride with an acidic polishing slurry comprising:
- (a) from about <u>0.1 to about 3.5 %</u> <del>0.1 to about 6%</del>, by weight, of a colloidal silica abrasive,
- (b) from about 1 to about 6%, 0.5 to about 10%, by weight, of a fluoride salt

wherein the colleidal cilica abracive is present in a quantity ranging from about 0.1 to about 3.5% by weight and the fluoride call is present in a quantity of from about 1 to about 6%, by weight, and

- (c) wherein the slurry has a pH ranging from about 2 to about 6.
- 11. (Currently Amended) The <u>method</u> <del>peliching clurry</del> according to Claim 10, wherein the fluoride salt is an ammonium salt.
  - 12. (Currently Amended) The <u>method</u> <del>poliching clurry</del> according to Claim <u>103</u>, wherein the fluoride salt is ammonium fluoride or ammonium hydrogen fluoride.
- 13. (Currently Amended) The <u>method</u> poliching clurry according to Claim 10 4, wherein the fluoride salt is ammonium hydrogen fluoride.
- 14. (Currently Amended) The method pelishing elumy according to Claim
  10, wherein the colloidal silica has a mean particle size of from about 10 nm to about
  1 μm.
- 15. (Currently Amended) The <u>method</u> polishing clurry-according to Claim 147, wherein the colloidal silica has a mean particle size of from about 20 nm to about 100 nm.